TOSHIBA CCD IMAGE SENSOR CCD (Charge Coupled Device)

# **TCD2901D**

The TCD2901D is a high sensitive and low dark current 10550 elements×3 line CCD color image sensor which includes CCD drive circuit and clamp circuit. The sensor is designed for scanner. The device contains a row of 10550 elements×3 line photodiodes which provide a 48 lines / mm (1200DPI) across a A4 size paper. The device is operated by 5 V pulse, and 12 V power supply.

### **FEATURES**

• Number of Image Sensing Elements

: 10550 elements×3 line

Image Sensing Element Size

: 4μm by 4μm on 4μm centers

Photo Sensing Region : High sensitive and low dark current

PN photodiode

• Distance Between Photodiode Array: 48µm (12 lines)

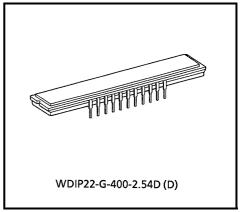
• Clock : 2 phase (5 V)

Power Supply
 12 V Power Supply Voltage

• Internal Circuit : Clamp circuit

• Package : 22 pin CERDIP package

• Color Filter : Red, Green, Blue

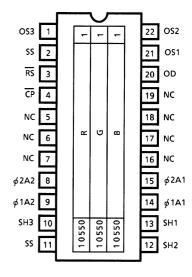


Weight: 5.2g (Typ.)

### PIN CONNECTION

#### **MAXIMUM RATINGS (Note 1) CHARACTERISTIC** SYMBOL **RATING** UNIT Clock Pulse Voltage $V_{\phi}A$ Shift Pulse Voltage $V_{SH}$ -0.3~8 Reset Pulse Voltage V<sub>RS</sub> Clamp Pulse Voltage $V_{\overline{CP}}$ -0.3~15 V Power Supply Voltage Vod Operating Temperature 0~60 °C Topr Storage Temperature T<sub>stg</sub> -25~85 °C

Note 1: All voltage are with respect to SS terminals (Ground).



(TOP VIEW)

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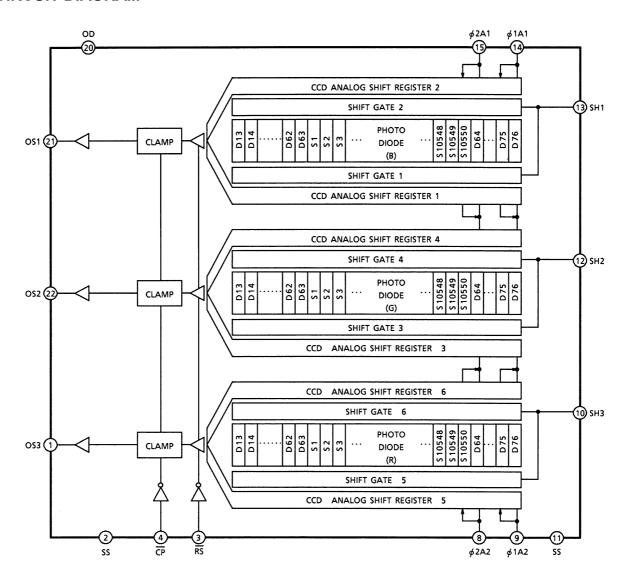
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### **CIRCUIT DIAGRAM**



### **PIN NAMES**

PIN No.	SYMBOL	NAME	PIN No.	SYMBOL	NAME
1	OS3	Signal Output 3 (Red)	22	OS2	Signal Output 2 (Green)
2	SS	Ground	21	OS1	Signal Output 1 (Blue)
3	RS	Reset Gate	20	OD	Power
4	CP	Clamp Gate	19	NC	Non Connection
5	NC	Non Connection	18	NC	Non Connection
6	NC	Non Connection	17	NC	Non Connection
7	NC	Non Connection	16	NC	Non Connection
8	Ψ2A2	Clock 2 (Phase 2)	15	Ψ2A1	Clock 1 (phase 2)
9	Ψ1A2	Clock 2 (Phase 1)	14	Ψ1A1	Clock 1 (phase 1)
10	SH3	Shift Gate 3	13	SH1	Shift Gate 1
11	SS	Ground	12	SH2	Shift Gate 2

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### **OPTICAL / ELECTRICAL CHARACTERISTICS**

(Ta = 25°C,  $V_{OD}$  = 12 V,  $V_{\phi}$  =  $V_{SH}$  =  $V_{\overline{RS}}$  =  $V_{\overline{CP}}$  = 5 V (PULSE),  $f_{\phi}$  = 0.5MHz,  $f_{\overline{RS}}$  = 1 MHz,  $t_{INT}$  = 11 ms, LIGHT SOURCE = A LIGHT SOURCE+CM500S FILTER (t = 1 mm), LOAD RESISTANCE = 100 k $\Omega$ )

CHARACTERISTIC		SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
	Red	R <sub>(R)</sub>	1.7	2.5	3.3		(Note 2)
Sensitivity	Green	R <sub>(G)</sub>	1.6	2.4	3.2	V / (lx·s)	
	Blue	R <sub>(B)</sub>	0.9	1.4	1.9		
Photo Response Non Uniformity		PRNU (1)	_	15	20	%	(Note 3)
Photo Response Non Officiality		PRNU (3)	_	3	12	mV	(Note 4)
Register Imbalance		RI	_	1	_	%	(Note 5)
Saturation Output Voltage		V <sub>SAT</sub>	2.9	3.5	_	V	(Note 6)
Saturation Exposure		SE	0.91	1.46	_	lx·s	(Note 7)
Dark Signal Voltage		$V_{DRK}$	_	0.5	2.0	mV	(Note 8)
Dark Signal Non Uniformity		DSNU	_	2.0	7.0	mV	(Note 8)
DC Power Dissipation		$P_{D}$	_	260	450	mW	
Total Transfer Efficiency		TTE	92	98	_	%	
Output Impedance		Z <sub>O</sub>	_	0.3	1.0	kΩ	
DC Compensation Output Voltage		V <sub>OS</sub>	4.0	5.0	6.0	V	(Note 9)
Random Noise		$N_{D\sigma}$	_	0.8	_	mV	(Note 10)
Reset Noise	V <sub>RSN</sub>	_	0.3	1.0	V	(Note 9)	
Masking Noise	V <sub>MS</sub>	_	0.2	1.0	V	(Note 9)	

Note 2: Sensitivity is defined for each color of signal outputs average when the photosensitive surface is applied with the light of uniform illumination and uniform color temperature.

Note 3: PRNU (1) is defined for each color on a single chip by the expressions below when the photosensitive surface is applied with the light of uniform illumination and uniform color temperature.

$$PRNU(1) = \frac{\Delta \chi}{\overline{\chi}} \times 100 (\%)$$

Where  $\bar{\chi}$  is average of total signal output and  $\Delta\chi$  is the maximum deviation from  $\bar{\chi}$ . The amount of incident light is shown below.

Red =  $1/2 \cdot SE$ 

Green =  $1/2 \cdot SE$ 

Bule =  $1/4 \cdot SE$ 

Note 4: PRNU (3) is defined as maximum voltage with next pixels, where measured at 5% of SE (Typ.).

Note 5: Register imbalance is defined as follows.

RI = 
$$\frac{\sum_{\sum}^{10549} |\chi n - \chi(n+1)|}{10549 * \frac{\pi}{\chi}} * 100(\%)$$

Note 6: V<sub>SAT</sub> is defined as minimum saturation output of all effective pixels.

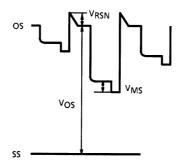
Note 7: Definition of SE

$$SE = \frac{VSAT}{RG}(Ix \cdot s)$$

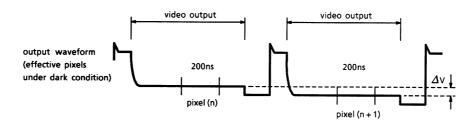
Note 8:  $V_{DRK}$  is defined as average dark signal voltage of all effective pixels. DSNU is defined as different voltage between  $V_{DRK}$  and  $V_{MDK}$  when  $V_{MDK}$  is maximum dark signal voltage.



Note 9: DC signal output voltage is defined as follows. Reset Noise Voltage is defined as follows.



Note 10: Random noise is defined as the standard deviation (sigma) of the output level difference between two adjacent effective pixels under no illumination (i.e. dark conditions) calculated by the following procedure.



- 1) Two adjacent pixels (pixel n and n+1) in one reading are fixed as measurement points.
- 2) Each of the output level at video output periods averaged over 200ns period to get V (n) and V (n+1).
- 3) V (n+1) is subtracted from V (n) to get  $\Delta V$ .

$$\Delta V = V(n)-V(n+1)$$

4) The standard deviation of  $\Delta V$  is calculated after procedure 2) and 3) are repeated 30 times (30 readings).

$$\Delta V = \frac{1}{30} \sum_{i=1}^{30} \!\! \left| \Delta V i \right| \quad \sigma = \sqrt{\frac{1}{30} \sum_{i=1}^{30} \!\! \left| \!\! \left| \Delta V i \right| - \overline{\Delta V} \right|^2}$$

- 5) Procedure 2), 3) and 4) are repeated 10 times to get sigma value.
- 6) 10 sigma values are averaged.

$$\overline{\sigma} = \frac{1}{10} \sum_{j=1}^{30} \sigma_j$$

7)  $\bar{\sigma}$  value calculated using the above procedure is observed  $\sqrt{2}$  times larger than that measured relative to the ground level. So we specify random noise as follows.

$$ND\sigma = \frac{1}{\sqrt{2}} - \frac{1}{\sqrt{2}}$$

### **OPERATING CONDITION**

CHARACTERISTIC		SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
Clock Pulse Voltage	"H" Level	$V_{\phi}A$	4.75	5.0	5.5	V	
Clock Fulse Voltage	"L" Level		0	_	0.3		
Shift Pulse Voltage	"H" Level	V <sub>SH</sub>	V <sub>φ</sub> A"H"–0.5	V <sub>φ</sub> A"H"	V <sub>φ</sub> A"H"	· V	(Note 11)
Still Fulse Voltage	"L" Level		0	0	0.5		
Reset Pulse Voltage	"H" Level	V <sub>RS</sub>	4.5	5.0	5.5	V	
Reset Fulse Voltage	"L" Level		0	0	0.5		
Clamp Pulse Voltage	"H" Level	\/	4.5	5.0	5.5	V	
Clamp Fulse Voltage	"L" Level	VCP	0	0	0.5	, v	
Power Supply Voltage		V <sub>OD</sub>	11.4	12.0	13.0	V	

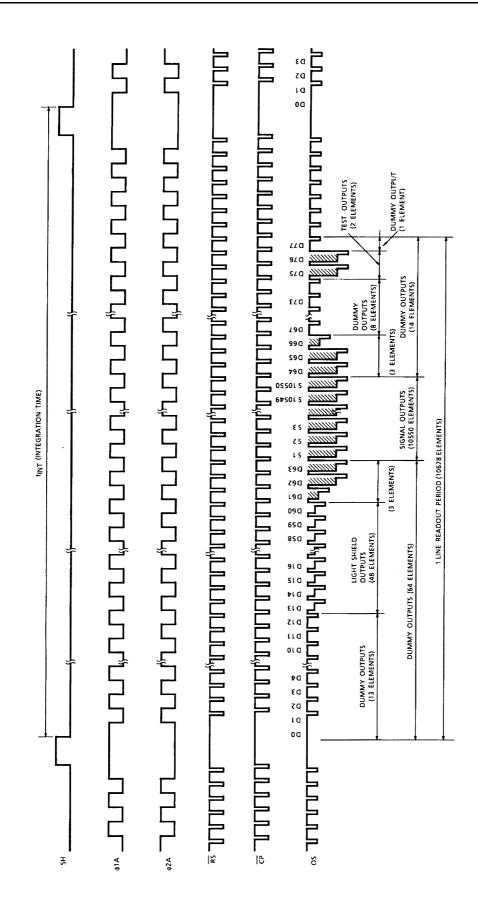
Note 11:  $V_{\phi}A$  "H" means the high level voltage of  $V_{\phi}A$  when SH pulse is high level.

## CLOCK CHARACTERISTICS (Ta = 25°C)

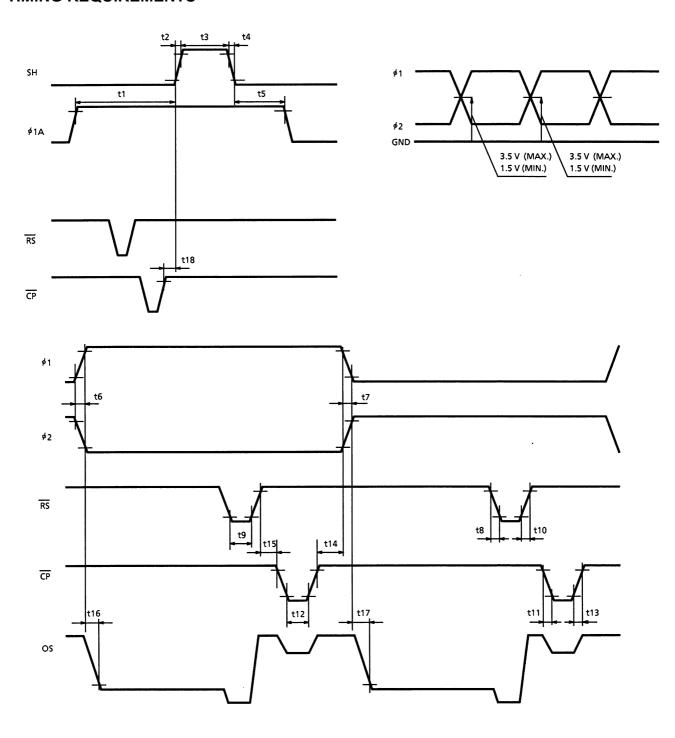
CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT
Clock Pulse Frequency	$f_{\phi}A$	0.15	0.5	2.5	MHz
Reset Pulse Frequency	fRS	0.3	1.0	5.0	MHz
Clamp Pulse Frequency	fCP	0.3	1.0	5.0	MHz
Clock Capacitance (Note 12)	СфА	_	350	450	pF
Shift Gate Capacitance	C <sub>SH</sub>	_	50	100	pF
Reset Gate Capacitance	CRS	_	10	20	pF
Clamp Gate Capacitance	CCP	_	10	20	pF

Note 12:  $V_{OD} = 12 V$ 





## **TIMING REQUIREMENTS**



## TIMING REQUIREMENTS (Cont'd)

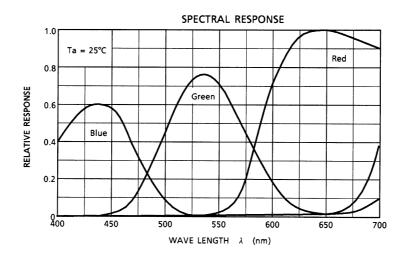
CHARACTERISTIC	SYMBOL	MIN.	TYP. (Note 13)	MAX.	UNIT
Pulse Timing of SH and φ <sub>1A</sub>	t1	110	1000	_	ns
Pulse Tilling of Sπ and φ <sub>1Α</sub>	t5	200	1000	_	
SH Pulse Rise Time, Fall Time	t2, t4	0	50	_	ns
SH Pulse width	t3	1000	2000	_	ns
φ <sub>1</sub> , φ <sub>2</sub> Pulse Rise Time, Fall Time	t6, t7	0	50	_	ns
RS Pulse Rise Time, Fall Time	t8, t10	0	20	_	ns
RS Pulse width	t9	45 (Note 15)	100	_	ns
CP Pulse Rise Time, Fall Time	t11, t13	0	20	_	ns
CP Pulse width	t12	40	100	_	ns
Pulse Timing of φ <sub>1A</sub> , φ <sub>2A</sub> and $\overline{\text{CP}}$	t14	20	40		ns
Pulse Timing of RS and CP	t15	45	100		ns
Video Data Delay Time (Note 14)	t16, t17	_	80	_	ns
Pulse Timing of SH and CP	t18	0	500	_	ns

Note 13: TYP. is the case of  $f_{\overline{RS}}$  =1.0 MHz.

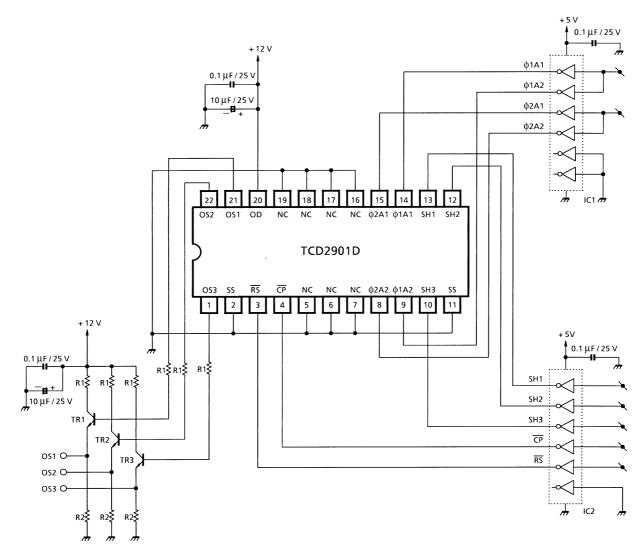
Note 14: Load resistance is 100 k $\Omega$ .

Note 15: In line clamp operation, t9 is 70 ns (MIN.).

## **TYPICAL SPECTRAL RESPONSE**



## **TYPICAL DRIVE CIRCUIT**



IC1, 2 : TC74AC04AP TR1, 2, 3 : 2SC1815-Y R1 : 150  $\Omega$  R2 : 1500  $\Omega$ 

### **CAUTION**

### 1. Window Glass

The dust and stain on the glass window of the package degrade optical performance of CCD sensor. Keep the glass window clean by saturating a cotton swab in alcohol and lightly wiping the surface, and allow the glass to dry, by blowing with filtered dry N<sub>2</sub>.

Care should be taken to avoid mechanical or thermal shock because the glass window is easily to damage.

### 2. Electrostatic Breakdown

Store in shorting clip or in conductive foam to avoid electrostatic breakdown.

### 3. Incident Light

CCD sensor is sensitive to infrared light.

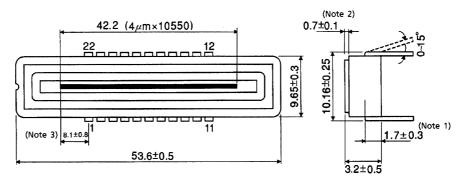
Note that infrared light component degrades resolution and PRNU of CCD sensor.

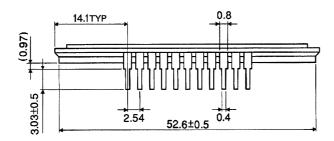
### 4. Lead Frame Forming

Since this package is not strong against mechanical stress, you should not reform the lead frame. We recommend to use a IC-inserter when you assemble to PCB.

### **PACKAGE DIMENSIONS**

WDIP22-G-400-2.54D (D) Unit: mm





Note 1: TOP OF CHIP TO BOTTOM OF PACKAGE

Note 2: GLASS THICKNESS (n = 1.5)

Note 3: No.1 SENSOR ELEMENT (S1) TO CENTER OF No.1 PIN.

Weight: 5.2g (Typ.)